



Cyclic Loading of Nanocrystalline FCC Metals *In Situ* in the TEM

10 April 2015

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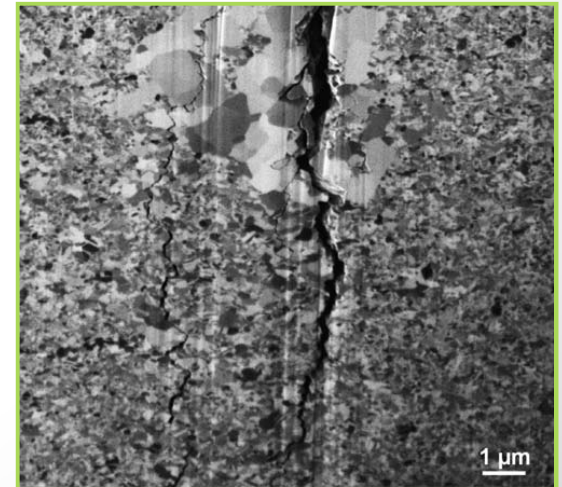
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Motivation

- Fatigue in bulk metals
 - Progressive microstructural change with cyclic loading
 - Often at loads below yield stress
 - Fatigue in nc metals
 - Grain boundary migration and grain growth
 - Crack initiation
 - What are the underlying mechanisms associated with these phenomena?
 - Pre-deformation microstructure
 - Grain and grain boundary orientations
- *In situ* TEM deformation is a tool capable of investigating these questions.



Execcharter, 2011.



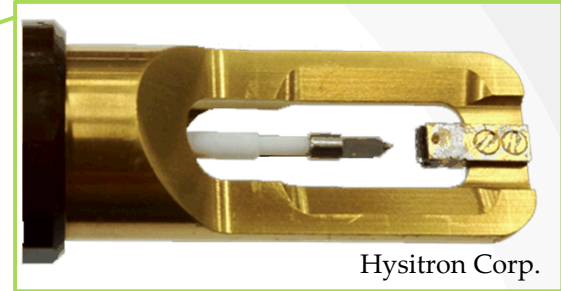
Padilla and Boyce, Exp Mech 2006.

Experimental Tools

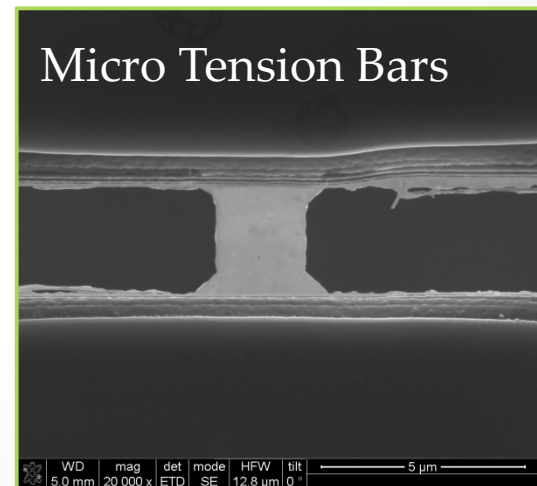
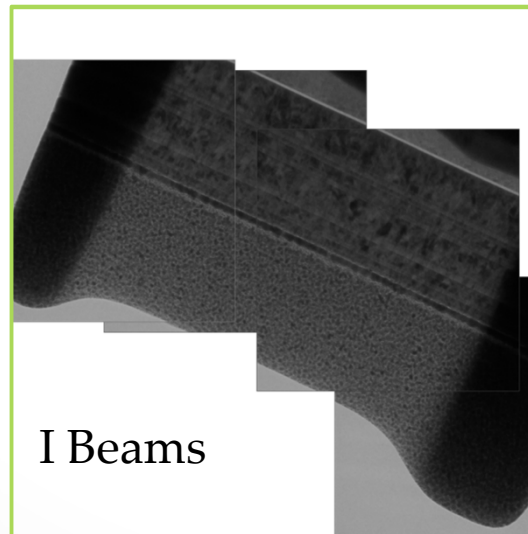
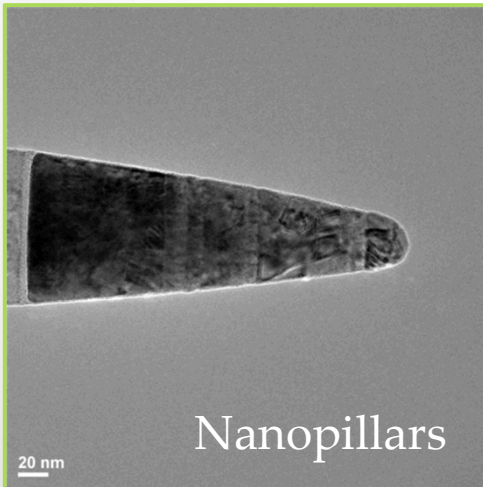
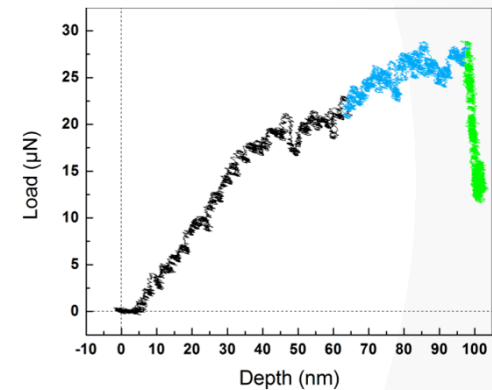


Hysitron PI95 *In Situ* Nanoindentation TEM Holder

- Sub nanometer displacement resolution
- Quantitative force information with μN resolution
- Concurrent real-time imaging by TEM

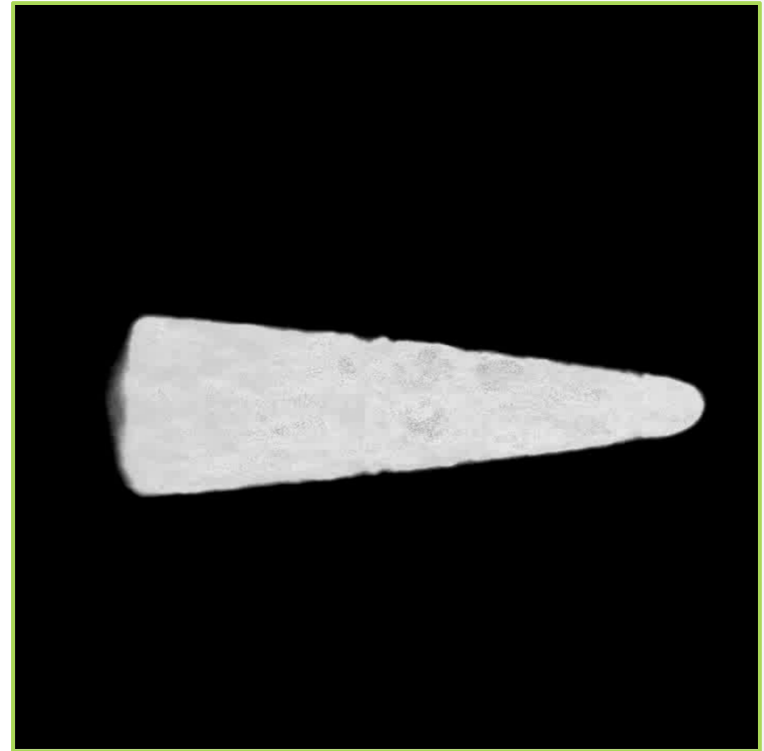
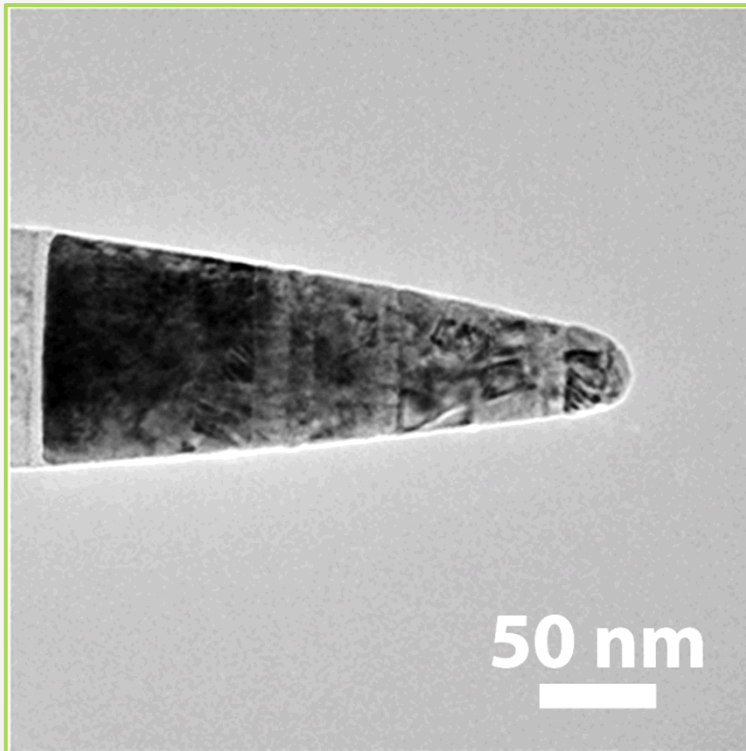


Hysitron Corp.



Nanopillar Fabrication

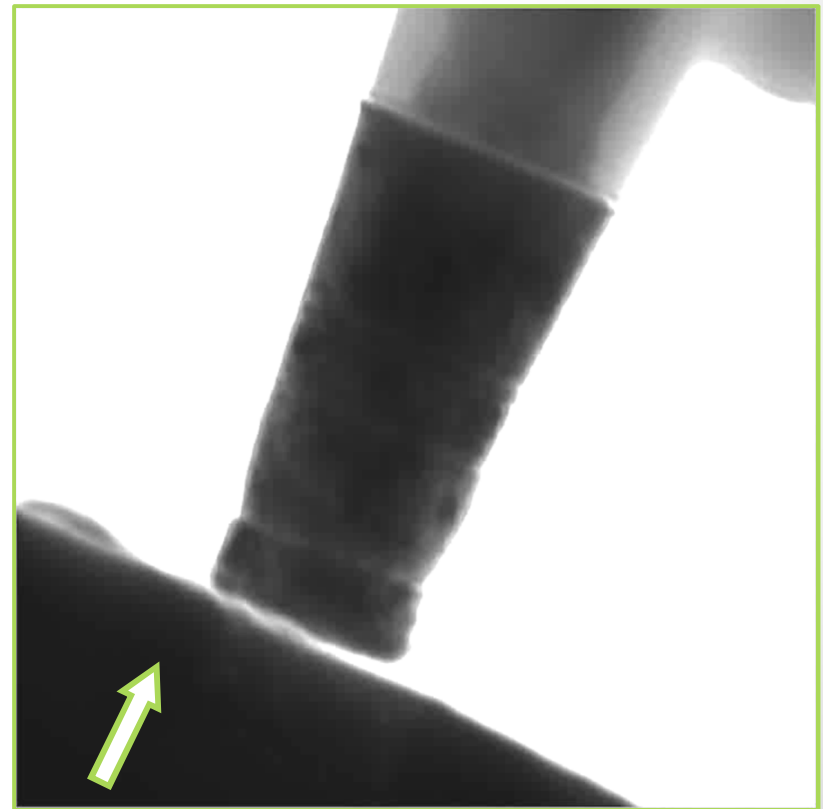
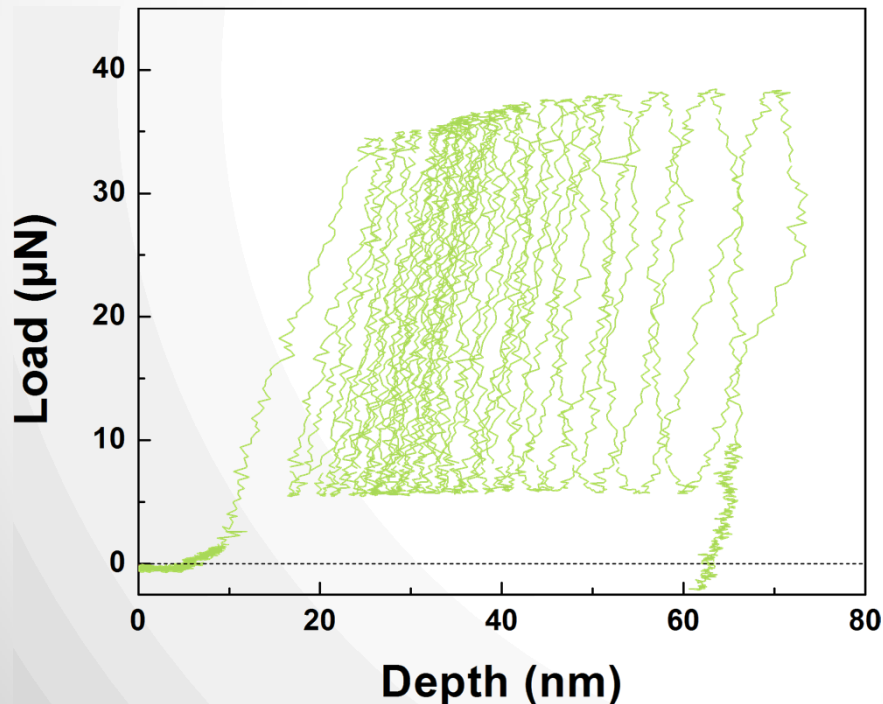
- FIB-milled from 500 nm PLD Ni on Si
 - ~100 nm base diameter
 - Conical geometry



- Mostly electron-transparent, easy geometry for stress calculations
- Small volume, susceptible to vibration and shear

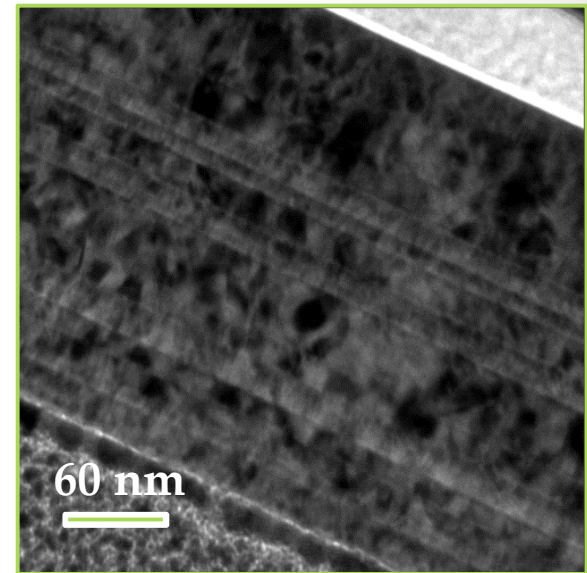
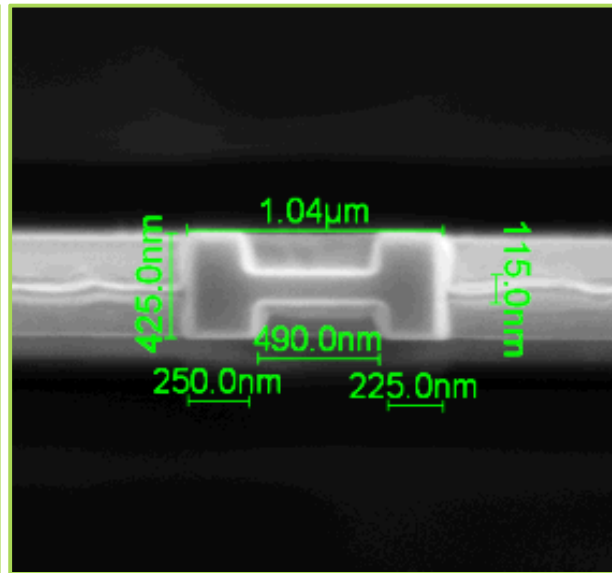
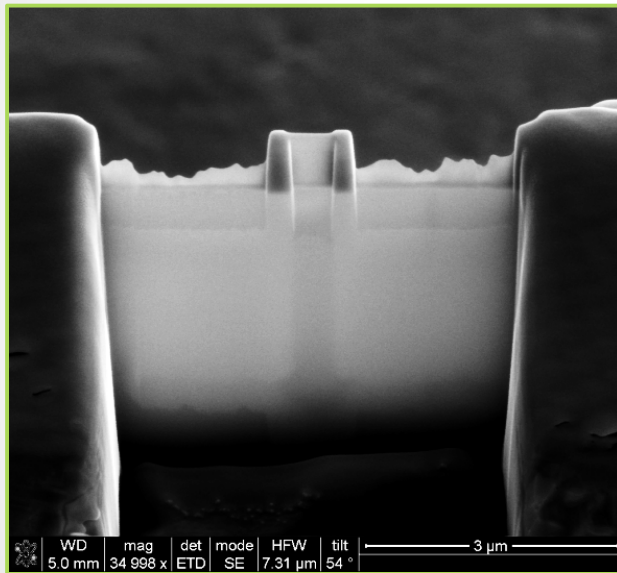
Pillar Compression

- Cyclic loading with increasing force amplitude
 - After a previous monotonic compression
 - 23 cycles to failure
- Failure initiated at notches



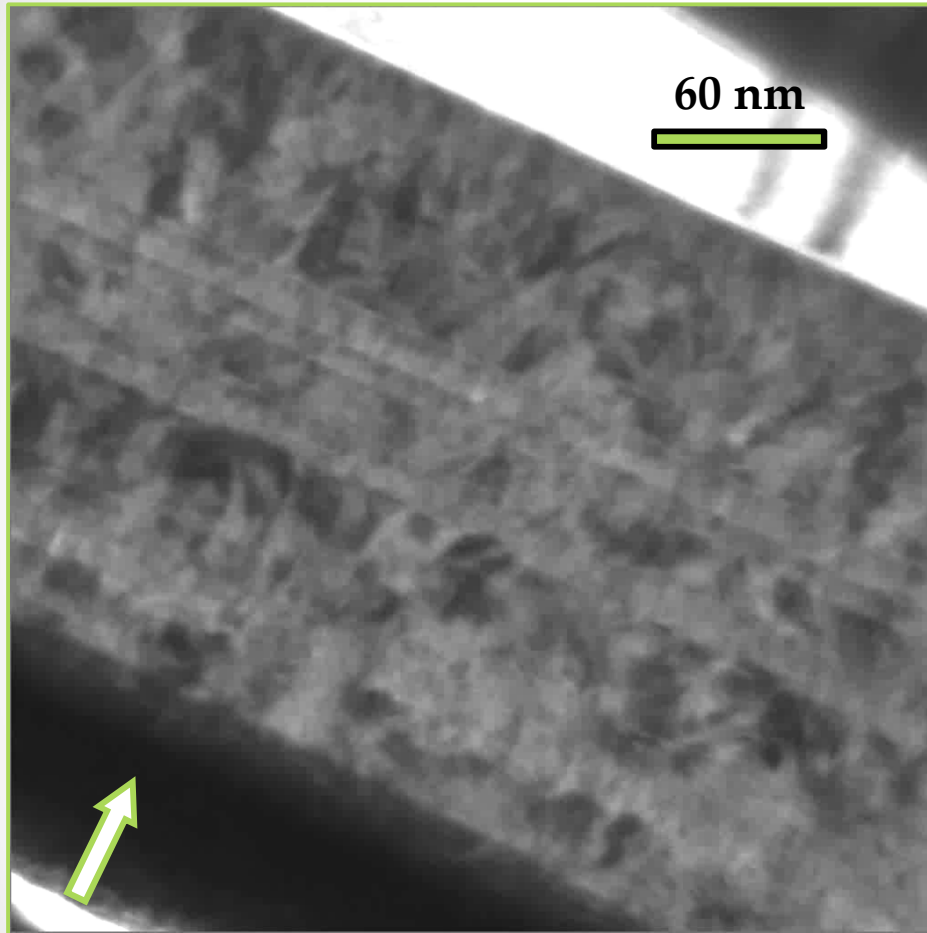
“I-Beam” Fabrication

- Wide pillars with transparent center and thicker side supports
- FIB-milled from same 500 nm PLD Ni on Si

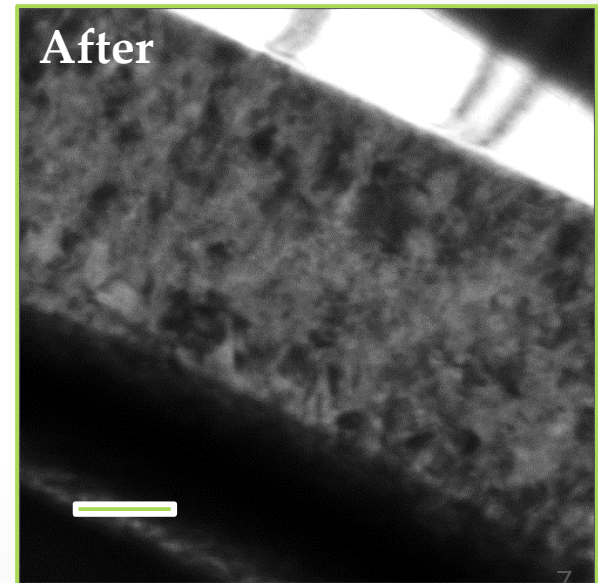
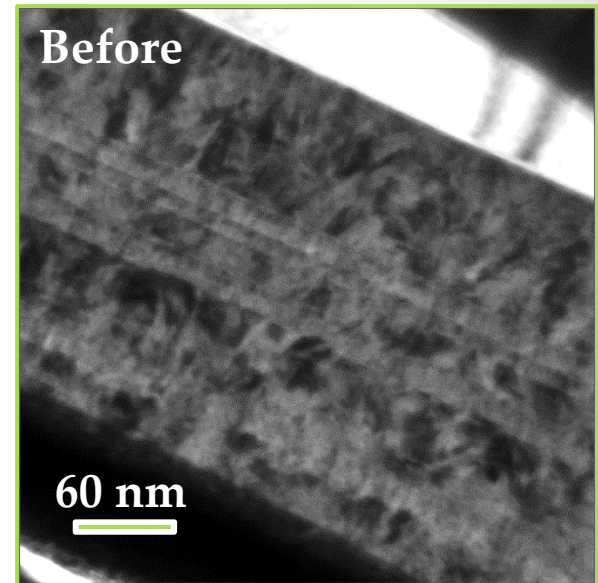


- Enhanced mechanical stability and larger viewable area
- More complicated force-displacement interpretation

I Beam Compression

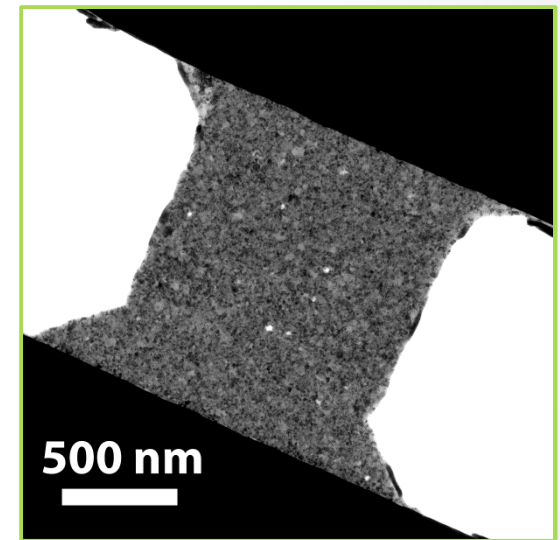
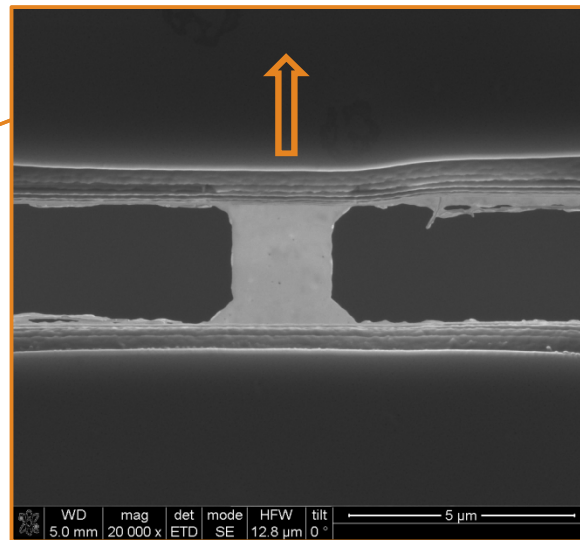
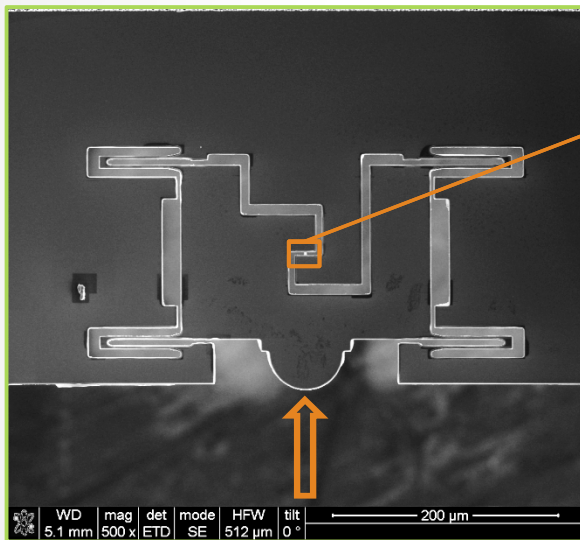


- Improved visualization
- Evidence of grain growth



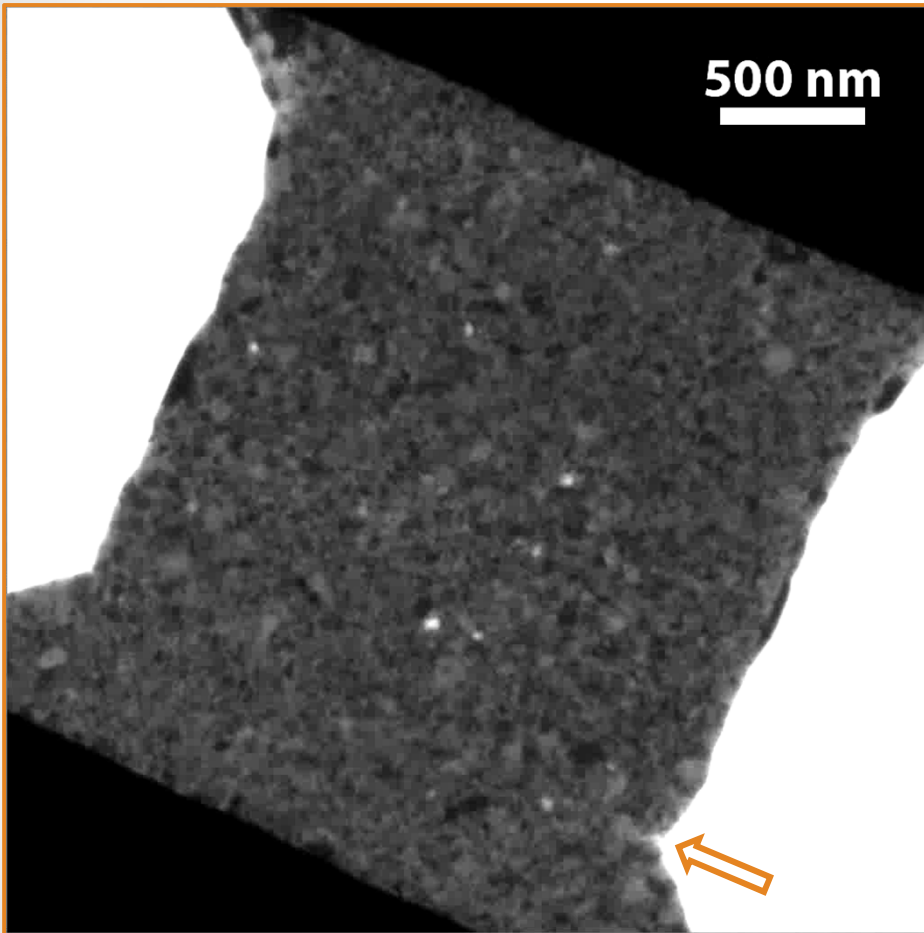
Tension Specimen Fabrication

- Hysitron “Push-to-Pull” devices
 - Microfabricated Si test frame
 - Cu film (75 nm) floated onto device, then FIB milled



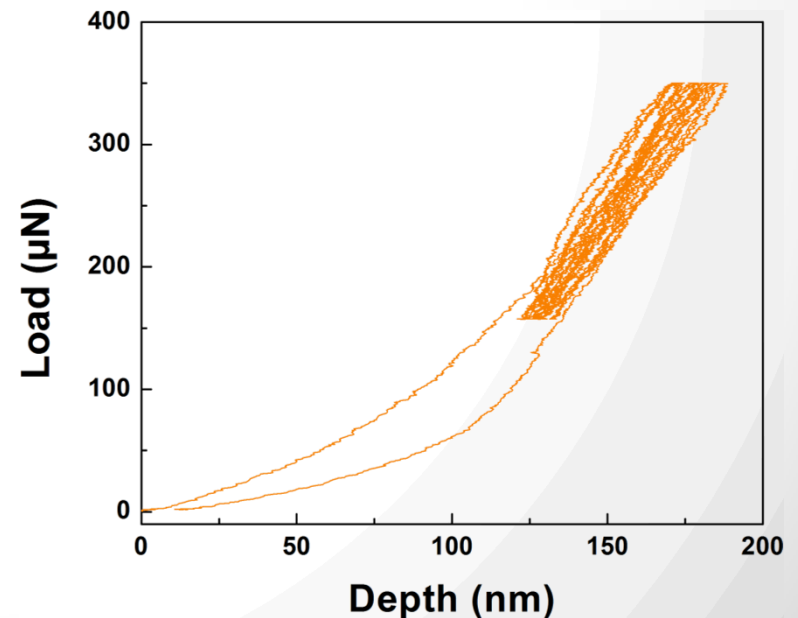
- Nearly pure tension, uniform cross sectional area, stable load frame
- Fragile, sensitive to shape of edges, issues with magnetic materials

Tension Testing

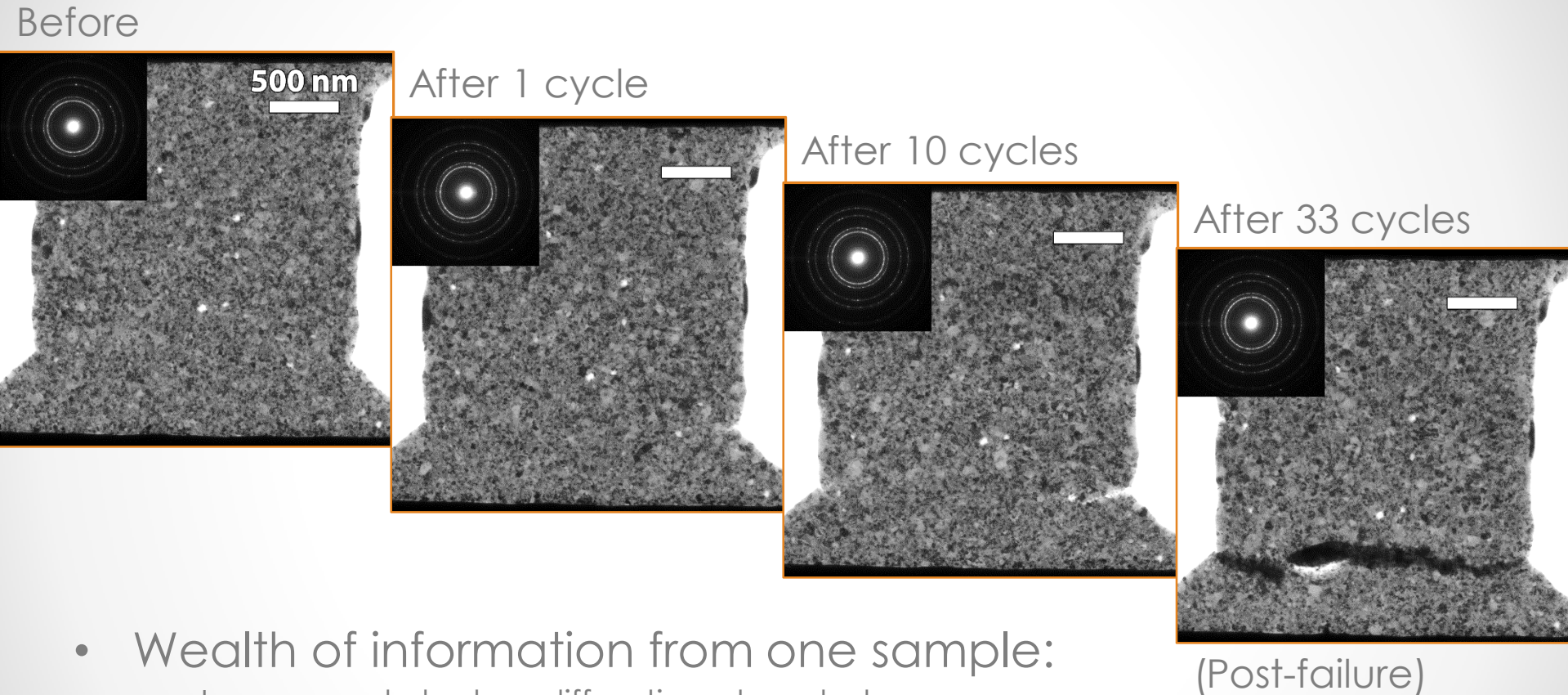


- Slow crack propagation
- Evidence of grain growth

- Cyclic loading:
 - Crack initiated in previous monotonic test
 - 9 cycles to ~87.5% of that load
 - 50 % unloading
 - Slow crack propagation



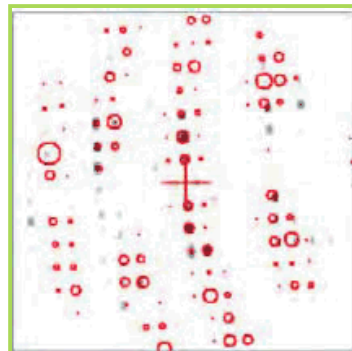
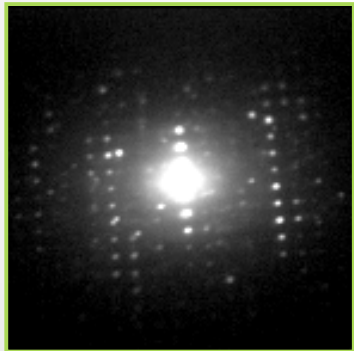
Cyclic Tension *In Situ*



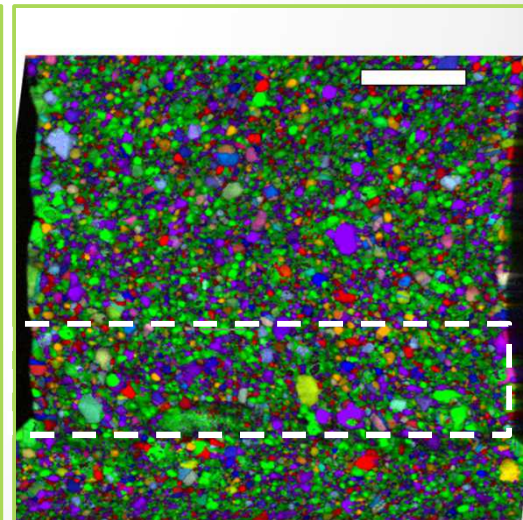
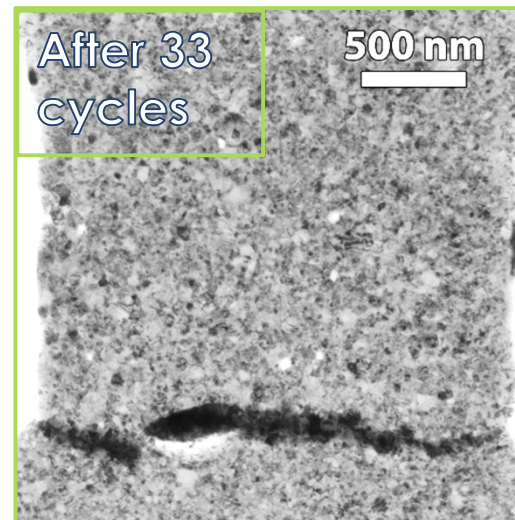
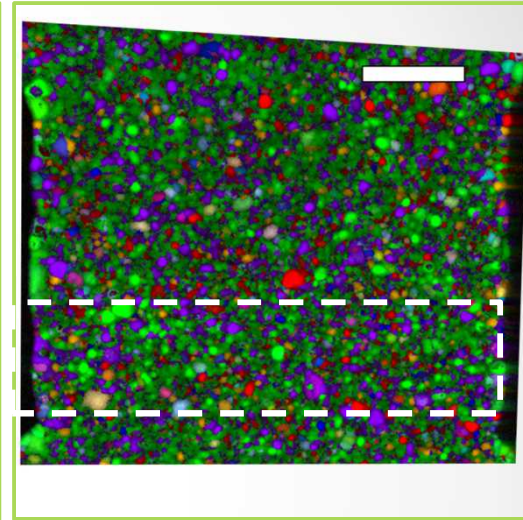
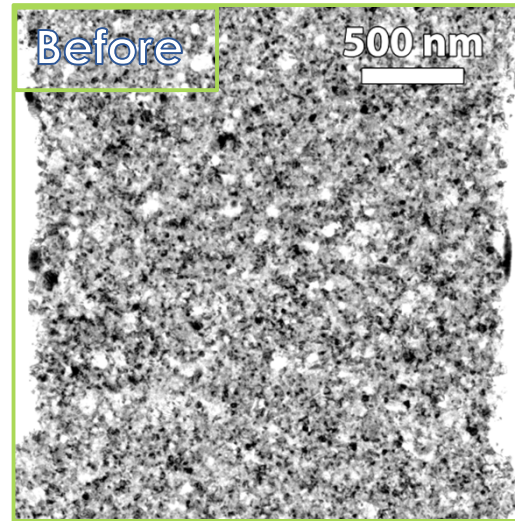
- Wealth of information from one sample:
 - Images and electron diffraction at each stage
 - Video and force/displacement during load cycles
- Microstructural change still elusive
 - Difficult to confirm and quantify

Quantifying Microstructural Change

- Combining orientation mapping with deformation
- EBSD-like capability in the TEM
 - Powerful analytical tools available

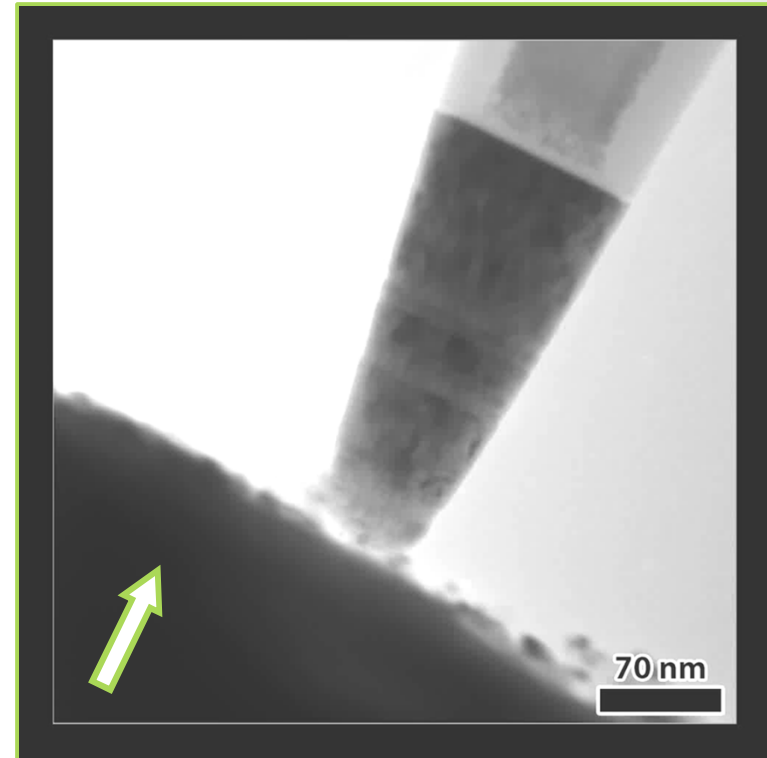
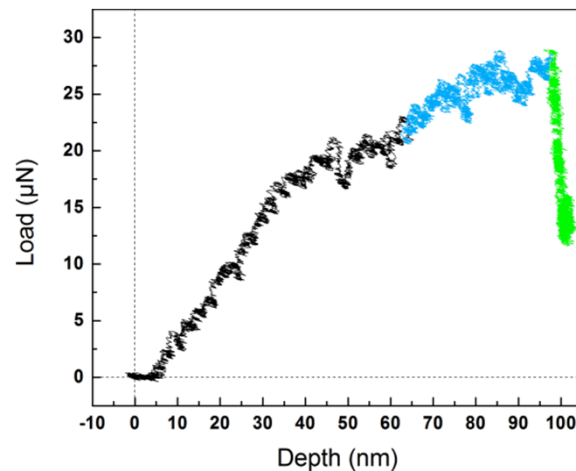
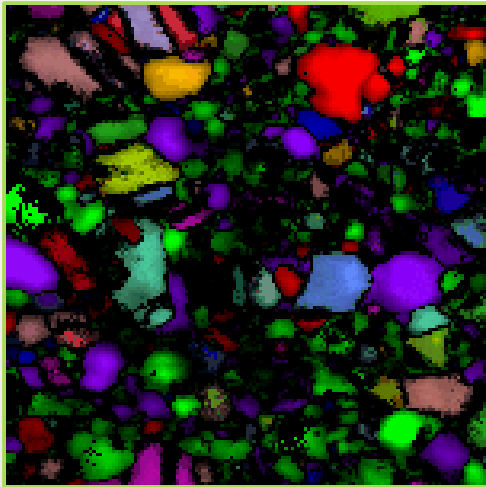


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Summary and Conclusions

- Preliminary low-cycle fatigue tests of nanocrystalline Ni and Cu performed in the TEM
 - Grain growth observed
 - Demonstrated feasibility of these methods



Acknowledgements: S. Bhowmick, L. Kuhn (Hysitron), A. Darbal (AppFive), D.P. Adams, M.T. Marshall, and C. Sobczak. This work was fully supported by the Division of Materials Science and Engineering, Office of Basic Energy Sciences, U.S. Department of Energy.